

Features

- -30V/-8.4A,
 $R_{DS(ON)} = 19m\Omega(Typ.)@V_{GS} = -10V$
 $R_{DS(ON)} = 29m\Omega(Typ.)@V_{GS} = -4.5V$
- Low $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

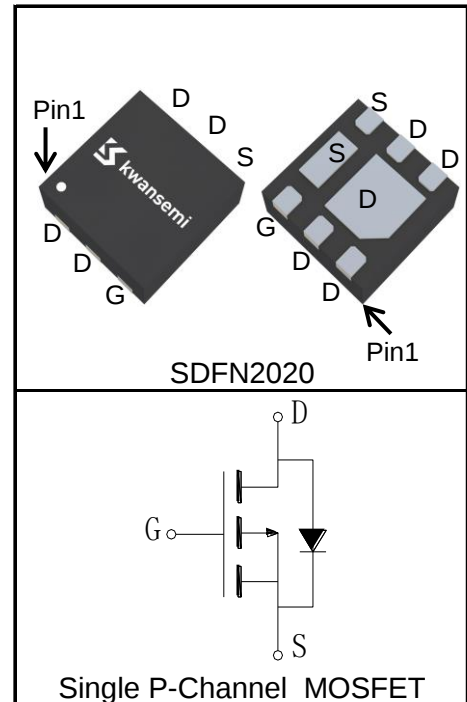
Applications

- Load Switch
- PWM Applications
- Power Management



Halogen-Free

Pin Description



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_{Jmax}	Maximum Junction Temperature	150	$^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
I_S	Diode Continuous Forward Current	$T_C = 25^\circ\text{C}$ -2.9	A
Mounted on Large Heat Sink			
$I_{DP}^{(1)}$	Pulse Drain Current	$T_A = 25^\circ\text{C}$ -33	A
$I_D^{(2)}$	Continuous Drain Current ($V_{GS} = -10V$)	$T_A = 25^\circ\text{C}$ -8.4	A
		$T_A = 70^\circ\text{C}$ -6.7	
P_D	Maximum Power Dissipation	$T_A = 25^\circ\text{C}$ 2.5	W
		$T_A = 70^\circ\text{C}$ 1.6	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	4	$^\circ\text{C/W}$
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	50	$^\circ\text{C/W}$
Drain-Source Avalanche Ratings			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	90	mJ

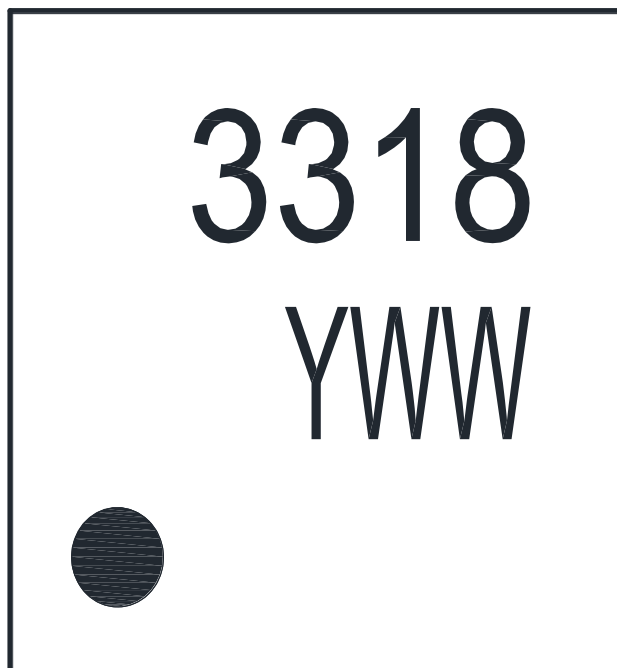
Electrical Characteristics ($T_C=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	KS3318UB2			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	μA
		T _J =125°C			-30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250μA	-1.1	-1.6	-2.3	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
R _{DS(ON)} ⑤	Drain-Source On-state Resistance	V _{GS} =-10V, I _{DS} =-8A		19	25	mΩ
		V _{GS} =-4.5V, I _{DS} =-6A		29	39	mΩ
Diode Characteristics						
V _{SD} ⑤	Diode Forward Voltage	I _{SD} =-8A, V _{GS} =0V		-0.86	-1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =-8A, dI _{SD} /dt=-100A/μs		18		ns
Q _{rr}	Reverse Recovery Charge			39		nC
Dynamic Characteristics ⑥						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		14		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, Frequency=1.0MHz		1560		pF
C _{oss}	Output Capacitance			180		
C _{rss}	Reverse Transfer Capacitance			145		
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-15V, I _{DS} =-8A, V _{GEN} =-10V, R _G =3Ω		10		ns
t _r	Turn-on Rise Time			14		
t _{d(OFF)}	Turn-off Delay Time			56		
t _f	Turn-off Fall Time			31		
Gate Charge Characteristics ⑥						
Q _g	Total Gate Charge	V _{DS} =-15V, V _{GS} =-10V, I _{DS} =-8A		20		nC
Q _{gs}	Gate-Source Charge			4.2		
Q _{gd}	Gate-Drain Charge			4.9		

- Notes:
- ① Pulse width limited by safe operating area.
 - ② Calculated continuous current based on maximum allowable junction temperature.
 - ③ When mounted on 1 inch square copper board, $t \leq 10\text{sec}$. The value in any given application depends on the user's specific board design.
 - ④ Limited by T_{Jmax} , Starting $T_J = 25^{\circ}\text{C}$, $I_{ASmax} = -19A$, $L=0.5\text{mH}$, $V_{DD} = -20V$, $R_G = 25\Omega$, $V_{GS}=-10V$. Part not recommended for use above this value.
 - ⑤ Pulse test; Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
 - ⑥ Guaranteed by design, not subject to production testing.

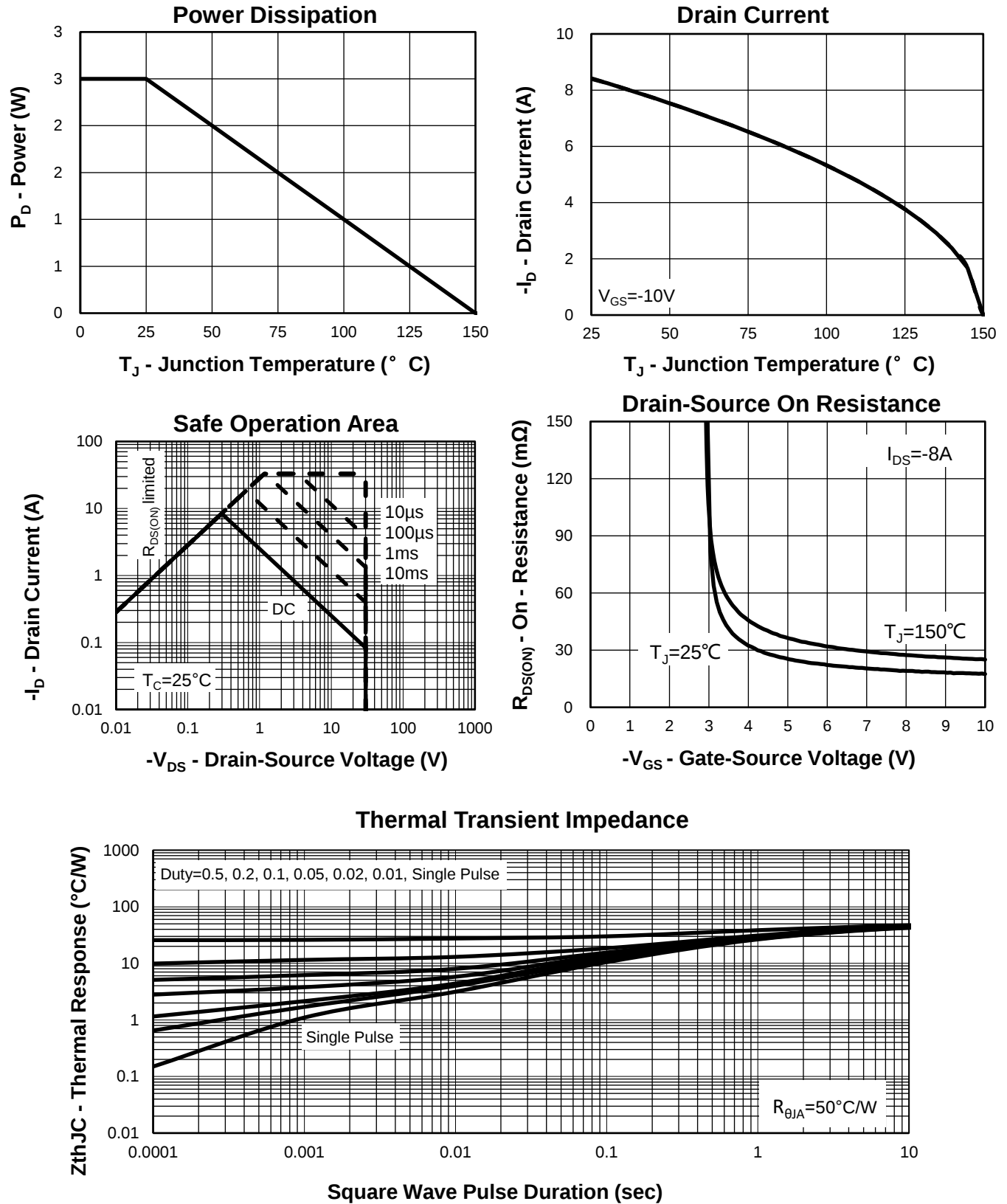
Ordering and Marking Information

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS3318UB2	SDFN2020	Tape&Reel	3000	7"	8mm

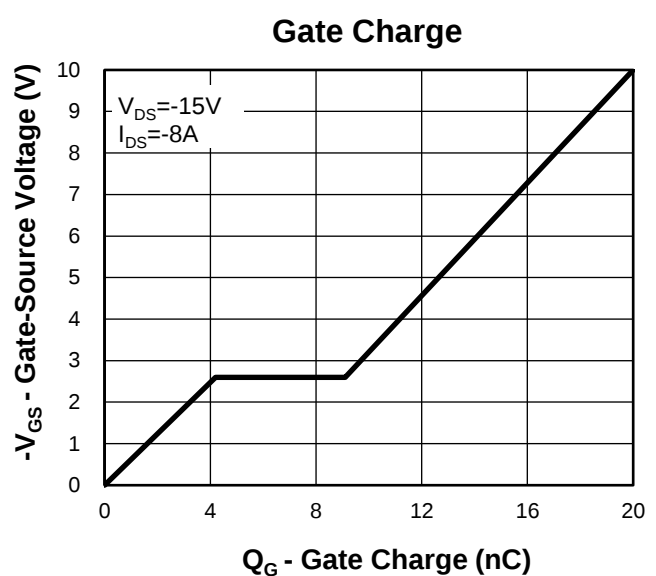
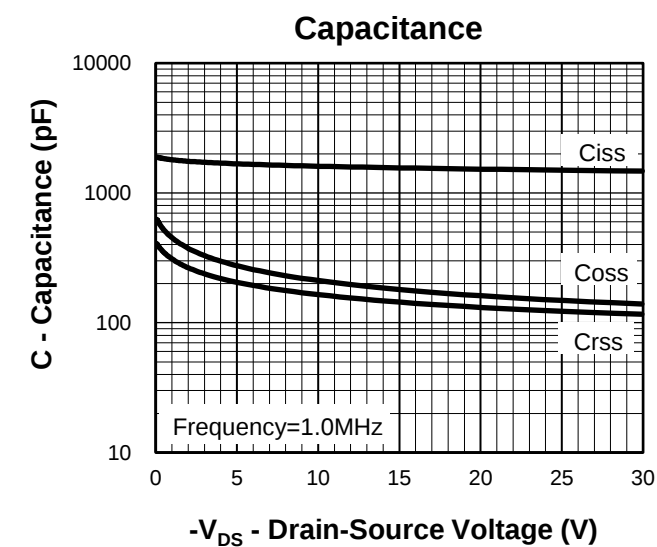
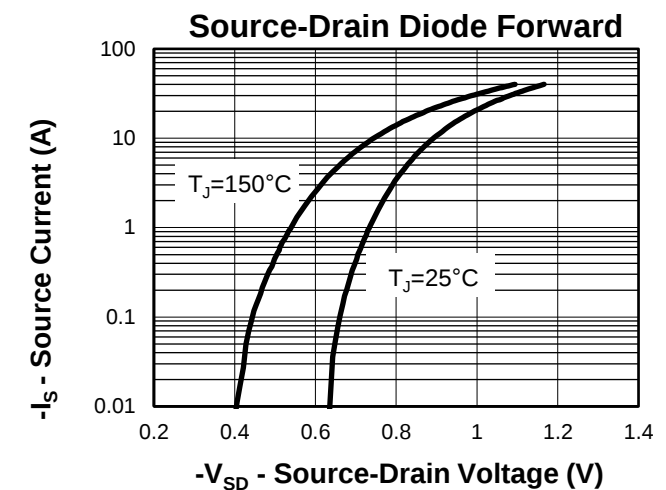
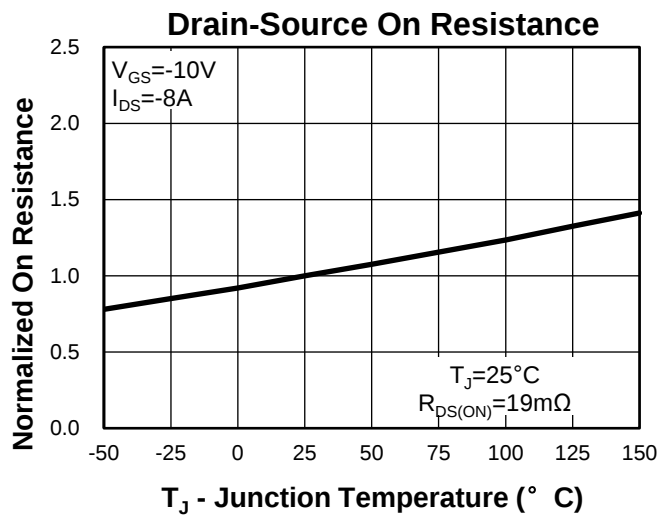
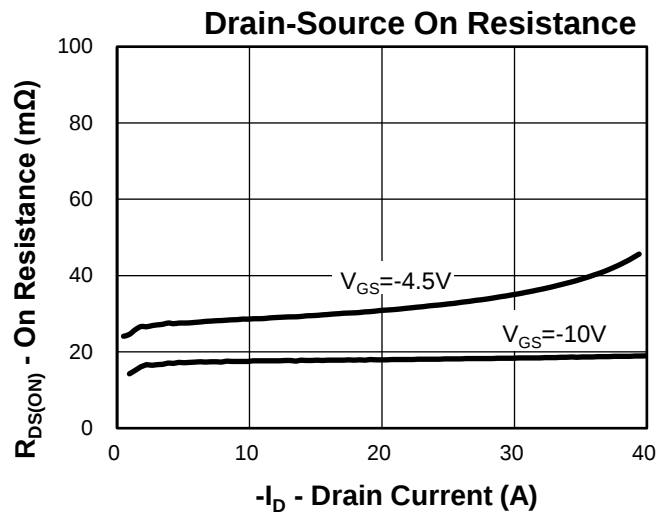
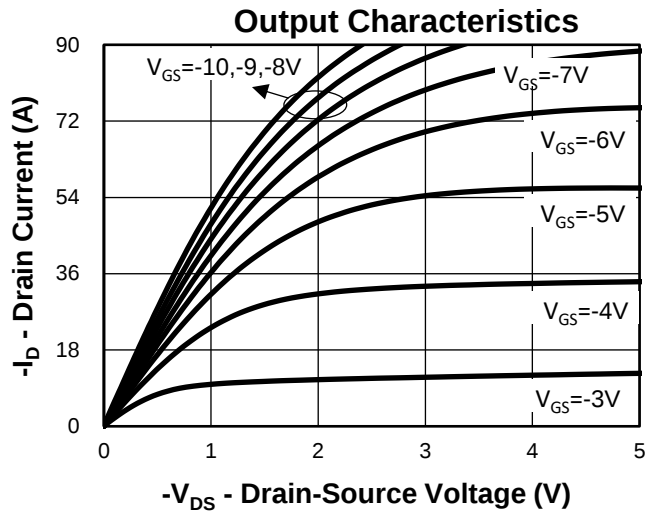


Y =Year,2017-A,2018-B,etc.
WW =Week.

Typical Characteristics

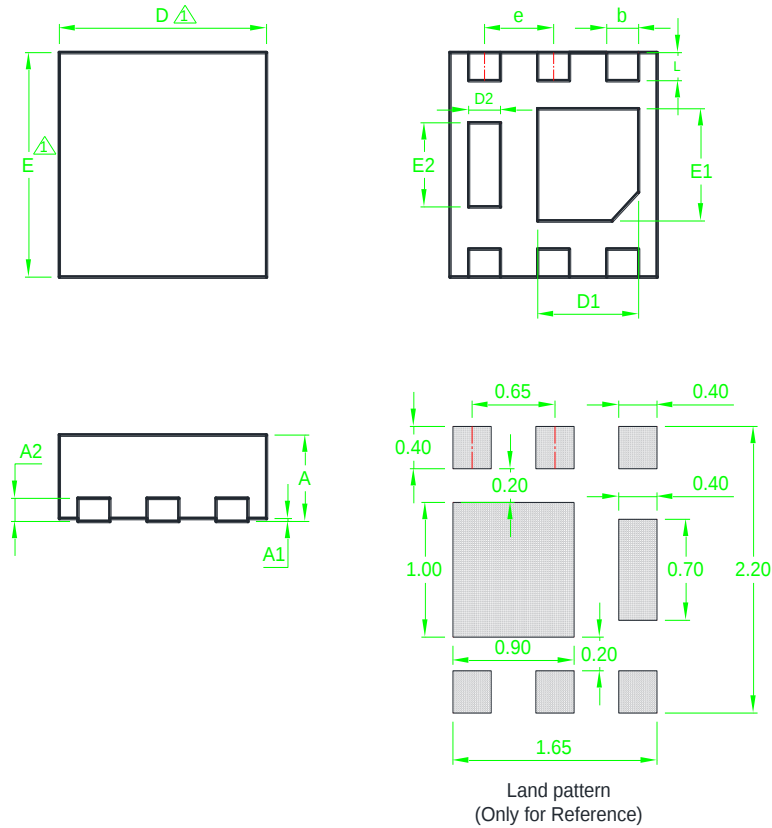


Typical Characteristics



Package Information

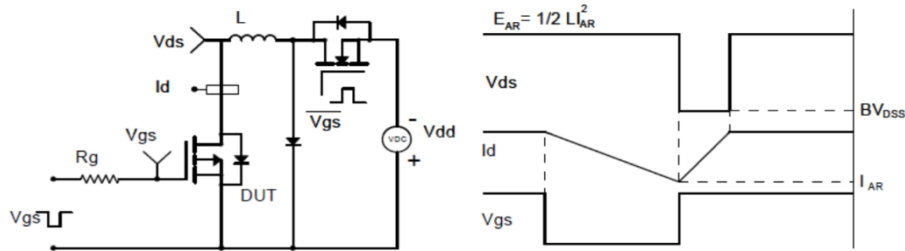
SDFN2020



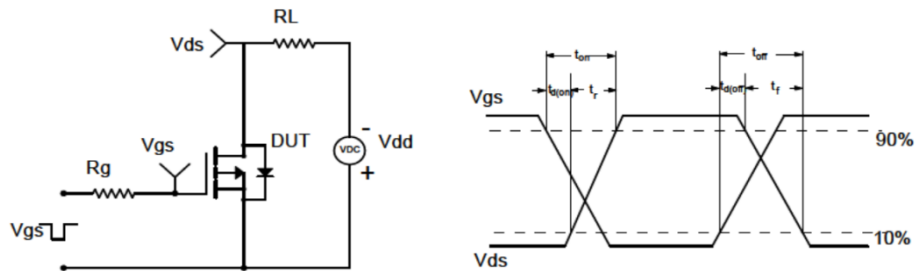
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	*	0.05	0.000	*	0.002
A2	0.203REF			0.008REF		
b	0.25	0.30	0.35	0.010	0.012	0.014
D	1.90	2.00	2.10	0.075	0.079	0.083
D1	0.80	0.90	1.00	0.031	0.035	0.039
D2	0.20	0.30	0.40	0.008	0.012	0.016
E	1.90	2.00	2.10	0.075	0.079	0.083
E1	0.80	0.95	1.10	0.031	0.037	0.043
E2	0.45	*	0.85	0.018	*	0.033
e		0.65BSC		0.026BSC		
L	0.20	*	0.35	0.008	*	0.014

 Dimensions D and E do not include mold flash protrusions or gate burrs.

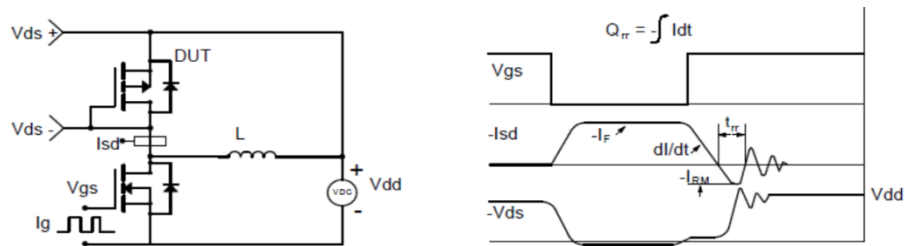
Avalanche Test Circuit and Waveforms



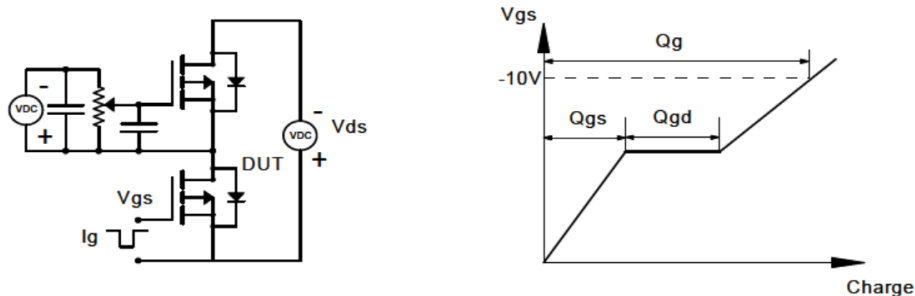
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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